

Excellent Integrated System Limited

Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

[STMicroelectronics](#)

[STTH602CFP](#)

For any questions, you can email us directly:

sales@integrated-circuit.com



STTH602C

Ultrafast recovery diode

Main product characteristics

$I_{F(AV)}$	2 x 3 A
V_{RRM}	200 V
T_j (max)	175° C
V_F (typ)	0.80 V
t_{rr} (typ)	14 ns

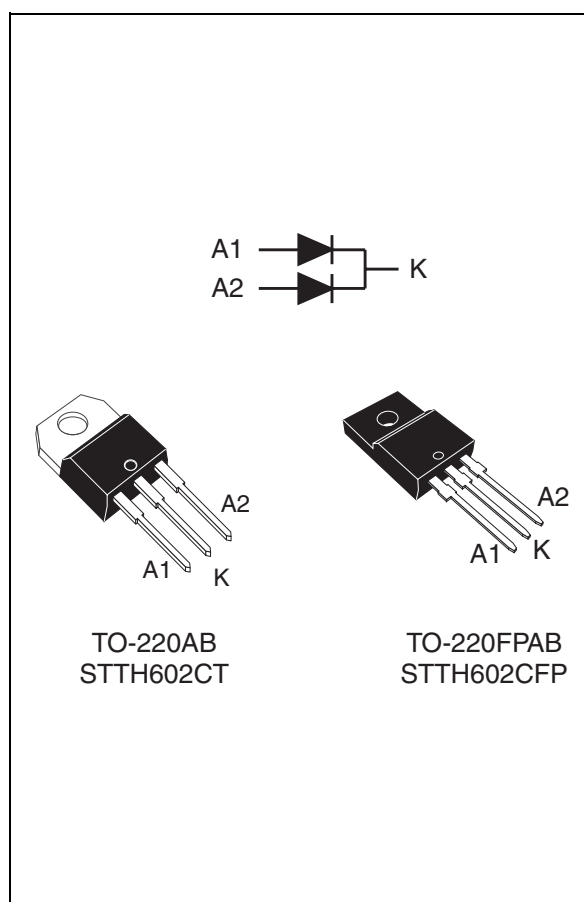
Features and benefits

- Suited for SMPS
- Low losses
- Low forward and reverse recovery time
- High surge current capability
- High junction temperature
- insulated package: TO-220FPAB

Description

Dual center tap diode suited for switch mode power supplies and high frequency DC to DC converters.

Packaged in TO-220AB and TO-220FPAB, this device is intended for use in low voltage high frequency inverters, free wheeling and polarity protection.



Order codes

Part Number	Marking
STTH602CT	STTH602C
STTH602CFP	STTH602C

Characteristics

STTH602C

1 Characteristics

Table 1. Absolute ratings (limiting values at T_j = 25° C, unless otherwise specified)

Symbol	Parameter		Value	Unit	
V _{RRM}	Repetitive peak reverse voltage		200	V	
I _{F(RMS)}	RMS forward current		22	A	
I _{F(AV)}	Average forward current, δ = 0.5	TO-220AB	Per diode T _c = 160° C	3	A
			Per device T _c = 155° C	6	
		TO-220FPAB	Per diode T _c = 150° C	3	A
			Per device T _c = 140° C	6	
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms Sinusoidal	60	A	
T _{stg}	Storage temperature range		-65 to + 175	° C	
T _j	Maximum operating junction temperature		175	° C	

Table 2. Thermal parameters

Symbol	Parameter		Value	Unit	
R _{th(j-c)}	Junction to case	TO-220AB	Per diode	5	° C/W
			Per device	3.0	
		TO-220FPAB	Per diode	7.5	
			Per device	5.25	
R _{th(c)}	Coupling	TO-220AB	Per diode	1	
		TO-220FPAB	Per diode	3	

When the two diodes 1 and 2 are used simultaneously:

$$\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)} (\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Typ	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25° C	V _R = V _{RRM}		3	μA
		T _j = 125° C		3	30	
V _F ⁽²⁾	Forward voltage drop	T _j = 25° C	I _F = 3 A	0.98	1.1	V
		T _j = 150° C		0.8	0.95	
		T _j = 25° C	I _F = 6 A	1.1	1.25	
		T _j = 150° C		0.9	1.05	

1. Pulse test: t_p = 5 ms, δ < 2 %

2. Pulse test: t_p = 380 μs, δ < 2 %

To evaluate the conduction losses use the following equation:

$$P = 0.85 \times I_{F(AV)} + 0.033 I_{F(RMS)}^2$$

STTH602C

Characteristics

Table 4. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ	Max.	Unit
t_{rr}	Reverse recovery time	$I_F = 1\text{ A}$, $di_F/dt = -100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$, $T_j = 25\text{ }^\circ\text{C}$		14	20	ns
		$I_F = 1\text{ A}$, $di_F/dt = -50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$, $T_j = 25\text{ }^\circ\text{C}$		21	30	
I_{RM}	Reverse recovery current	$I_F = 3\text{ A}$, $di_F/dt = 200\text{ A}/\mu\text{s}$, $V_R = 160\text{ V}$, $T_j = 125\text{ }^\circ\text{C}$		4	5.5	A
t_{fr}	Forward recovery time	$I_F = 3\text{ A}$, $di_F/dt = 200\text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$, $T_j = 25\text{ }^\circ\text{C}$		24		ns
V_{FP}	Forward recovery voltage	$I_F = 3\text{ A}$, $di_F/dt = 200\text{ A}/\mu\text{s}$, $T_j = 25\text{ }^\circ\text{C}$		3.7		V

Figure 1. Peak current versus duty cycle (per diode)

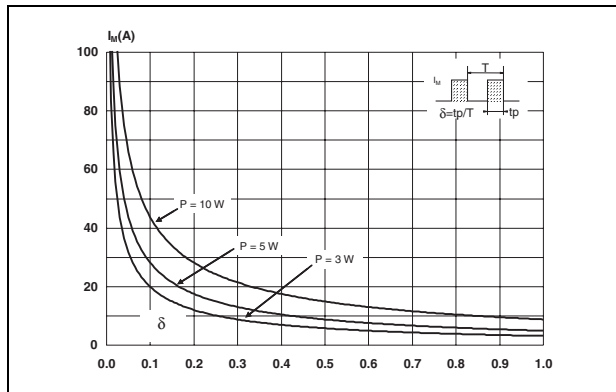


Figure 2. Forward voltage drop versus forward current (typical values per diode)

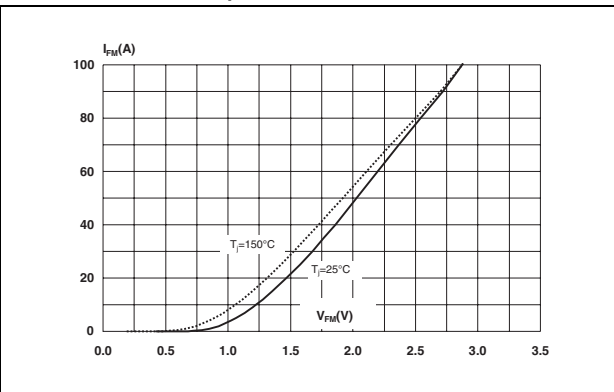


Figure 3. Forward voltage drop versus forward current (maximum values per diode)

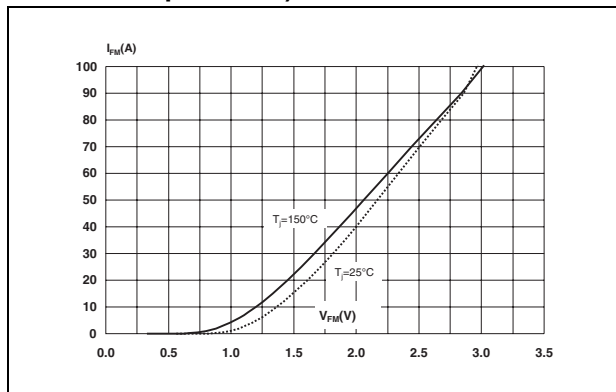
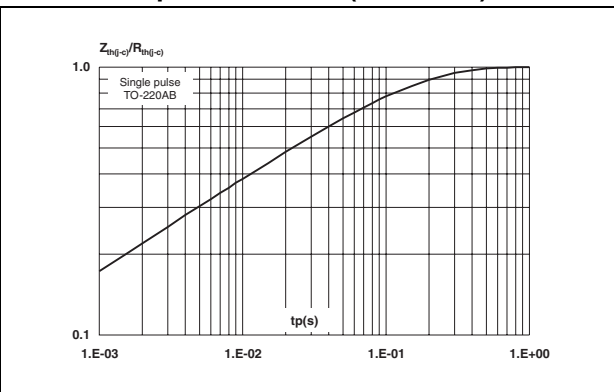


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration (T0-220AB)



Characteristics

STTH602C

Figure 5. Relative variation of thermal impedance junction to case versus pulse duration (TO-220FPAB)

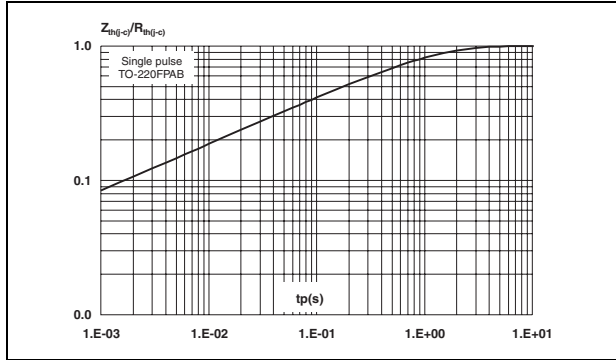


Figure 6. Junction capacitance versus reverse applied voltage (typical values per diode)

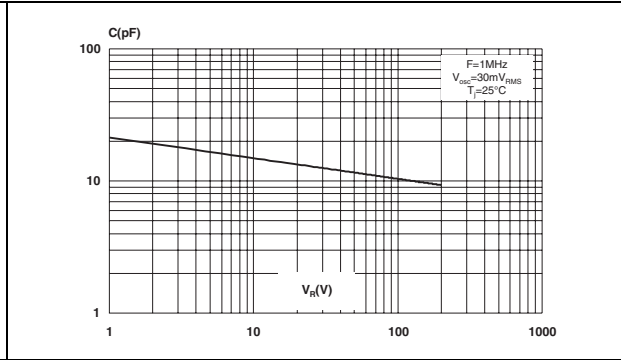


Figure 7. Reverse recovery charges versus di_F/dt (typical values)

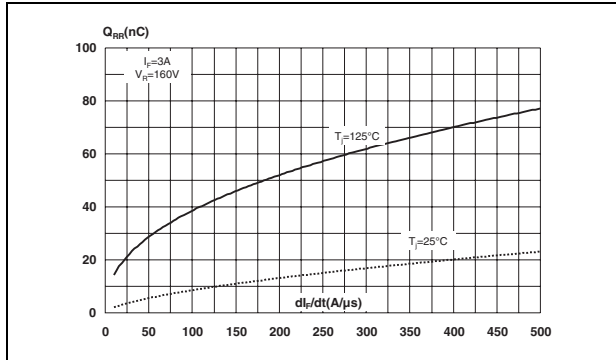


Figure 8. Reverse recovery time versus di_F/dt (typical values)

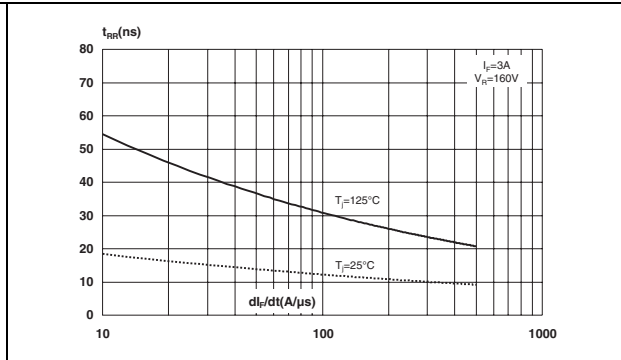


Figure 9. Peak reverse recovery current versus di_F/dt (typical values)

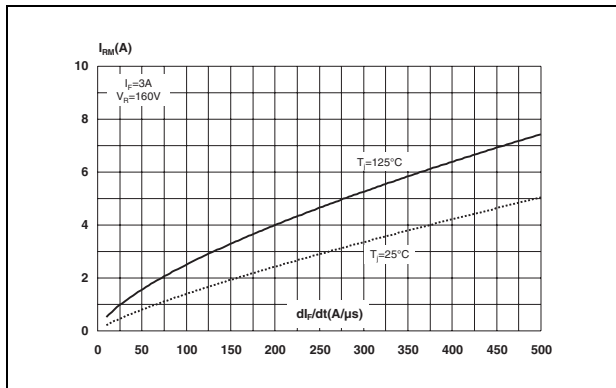
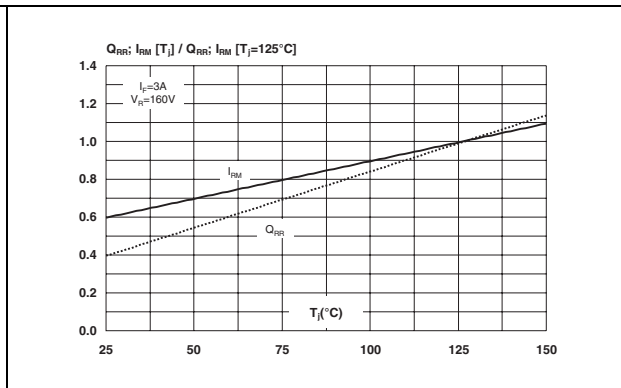


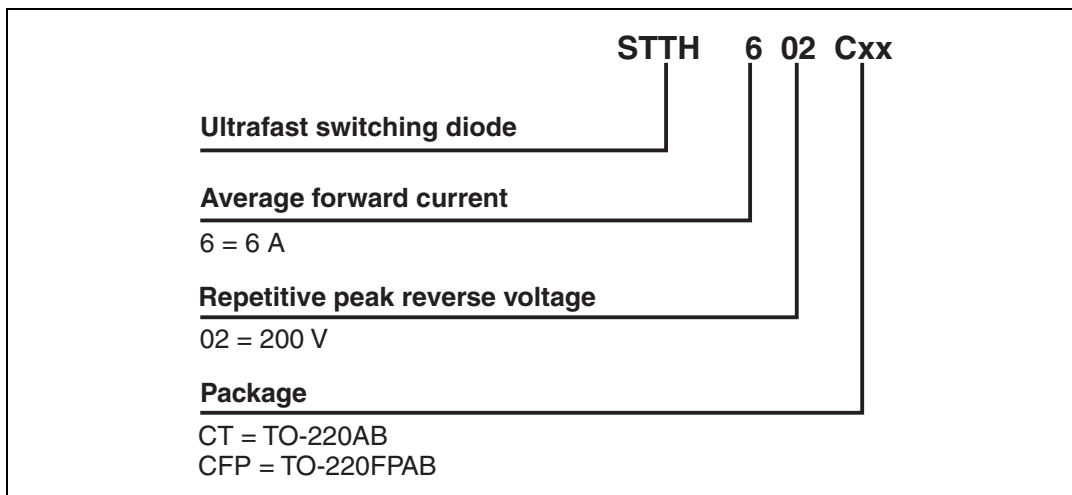
Figure 10. Dynamic parameters versus junction temperature



STTH602C

Ordering information scheme

2 Ordering information scheme



Package information

STTH602C

3 Package information

Epoxy meets UL94, V0

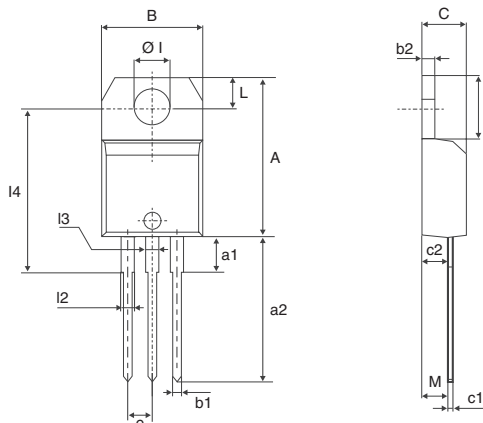
Cooling method: by conduction (C)

Recommended torque value: 0.8 Nm

Maximum torque value: 1.0 Nm

Table 5. TO-220AB Dimensions

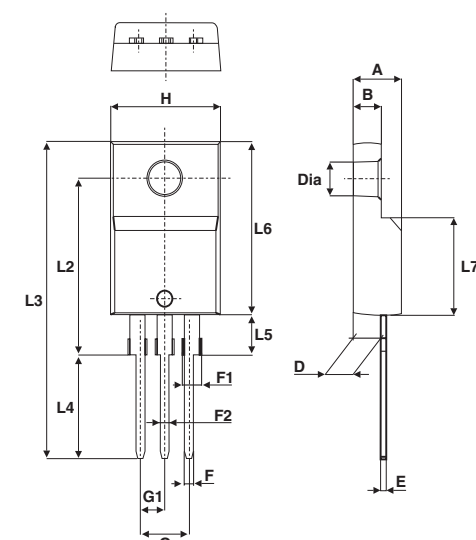
REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ	Max.	Min.	Typ	Max.
A	15.20		15.90	0.598		0.625
a1		3.75			0.147	
a2	13.00		14.00	0.511		0.551
B	10.00		10.40	0.393		0.409
b1	0.61		0.88	0.024		0.034
b2	1.23		1.32	0.048		0.051
C	4.40		4.60	0.173		0.181
c1	0.49		0.70	0.019		0.027
c2	2.40		2.72	0.094		0.107
e	2.40		2.70	0.094		0.106
F	6.20		6.60	0.244		0.259
ØI	3.75		3.85	0.147		0.151
I4	15.80	16.40	16.80	0.622	0.646	0.661
L	2.65		2.95	0.104		0.116
I2	1.14		1.70	0.044		0.066
I3	1.14		1.70	0.044		0.066
M		2.60			0.102	



STTH602C

Package information

Table 6. TO-220FPAB Dimensions



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
B	2.5	2.7	0.098	0.106
D	2.5	2.75	0.098	0.108
E	0.45	0.70	0.018	0.027
F	0.75	1	0.030	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.4	2.7	0.094	0.106
H	10	10.4	0.393	0.409
L2	16 Typ.		0.63 Typ.	
L3	28.6	30.6	1.126	1.205
L4	9.8	10.6	0.386	0.417
L5	2.9	3.6	0.114	0.142
L6	15.9	16.4	0.626	0.646
L7	9.00	9.30	0.354	0.366
Dia.	3.00	3.20	0.118	0.126

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

4 Ordering information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
STTH602CT	STTH602C	TO-220AB	2.23 g	50	Tube
STTH602CFP	STTH602C	TO-220FPAB	2 g	50	Tube

5 Revision history

Date	Revision	Description of Changes
05-Apr-2006	1	First issue

STTH602C

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED REPRESENTATIVE OF ST, ST PRODUCTS ARE NOT DESIGNED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS, WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2006 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com